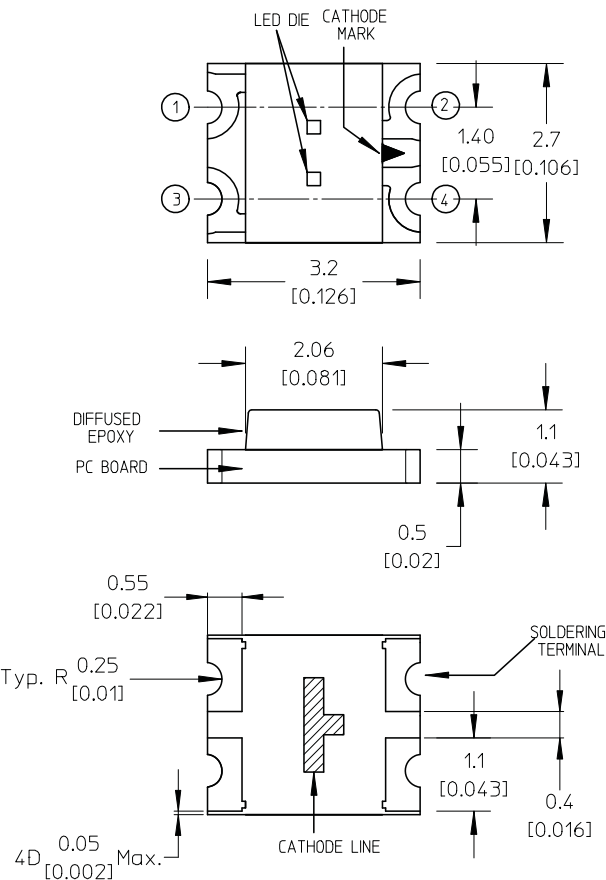
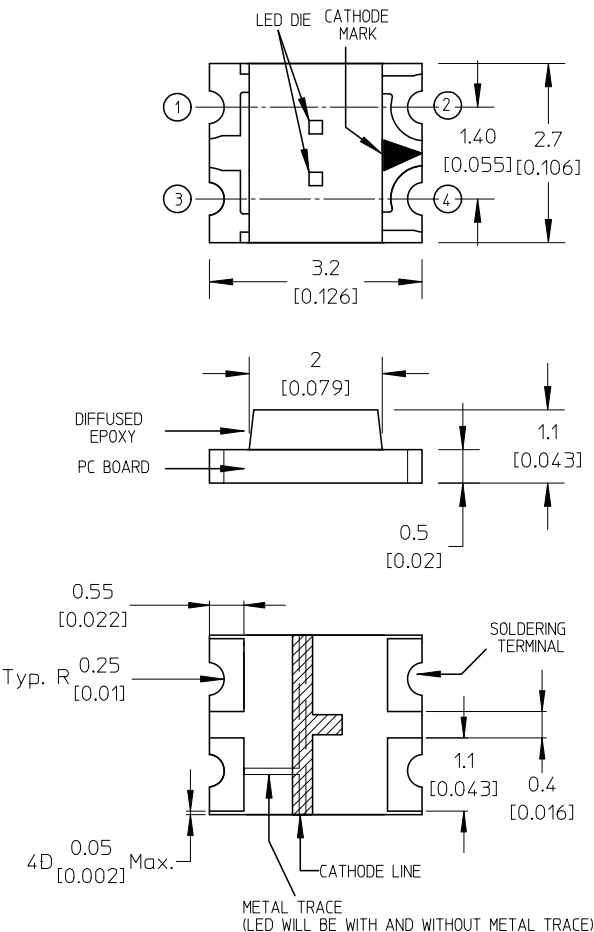


Package Dimensions

CHINA SOURCE



TAIWAN SOURCE



- NOTES:
1. ALL DIMENSIONS IN MILLIMETERS (INCHES).
 2. TOLERANCE IS ± 0.1 mm (± 0.004 IN.) UNLESS OTHERWISE SPECIFIED.

POLARITY	HSMF-C153	HSMF-C155	HSMF-C156	HSMF-C157	HSMF-C158
① — — ②	Yellow	Green	Green	Green	Green
③ — — ④	HER	HER	Yellow	Orange	Amber

Absolute Maximum Ratings at T_A = 25°C

Parameter	GaP	AlInGaP Green	AlInGaP Amber	Units
DC Forward Current ^[1]	20	20	25	mA
Power Dissipation ^[2]	65	52	60	mW
Reverse Voltage (I _R = 100μA)	5	5	5	V
LED Junction Temperature	95	95	95	°C
Operating Temperature Range	-40 to 85 °C			
Storage Temperature Range	-40 to 85 °C			
Soldering Temperature	See reflow soldering profile (Figure 6 & 7)			

Notes:

1. Derate linearly as shown in Figure 4 for temperature above 25°C.
2. Pulse condition of 1/10 duty and 0.1 msec. width.

Optical Characteristics at T_A = 25°C

Part Number	Luminous Intensity I _V ^[1] (mcd) @ 20mA		Color, Peak Wavelength λ _d (nm) Typical	Color, Dominant Wavelength λ _d ^[2] (nm) Typical	Viewing Angle 2θ _{1/2} ^[3] (Degrees) Typical
	Min.	Typ.			
GaP HER	2.50	10.0	630	626	170
GaP Yellow	2.50	8.0	589	586	170
GaP Green	4.00	15.0	570	572	170
GaP Orange	2.50	8.0	605	604	170
AlInGaP Green	28.50	45.0	570	572	170
AlInGaP Amber	28.50	55.0	595	592	170

Notes:

1. The luminous intensity I_V is measured at the peak of the spatial radiation pattern which may not be aligned with the mechanical axis of the LED package.
2. The dominant wavelength, λ_d, is derived from the CIE Chromaticity Diagram and represents the perceived color of the device.
3. λ_{1/2} is the off-axis angle where the luminous intensity is ½ the peak intensity.

Electrical Characteristics at T_A = 25°C

Part Number	Forward Voltage V _F (Volts) ^[1] @ I _F = 20mA		Reverse Breakdown VR (Volts) @ IR = 100μA	Capacitance C (pF) @VF = 0, f = 1Mhz	Thermal Resistance RθJ-P (°C/W)
	Typ.	Max.	Min.	Typ.	Typ.
GaP HER	2.1	2.6	5	5	325
GaP Yellow	2.1	2.6	5	6	325
GaP Green	2.2	2.6	5	9	325
GaP Orange	2.2	2.6	5	7	325
AlInGaP Green	2.1	2.4	5	22	325
AlInGaP Amber	1.9	2.4	5	45	325

Notes: The bicolor package contain two individual light sources of different color. The specifications above refer to each color of a particular package.

Color Bin Limits

GaP HER Color Bins ^[1]

Bin ID	Dominant Wavelength (nm)	
	Minimum	Maximum
-	620.0	635.0

Tolerance : ± 1 nm

GaP Yellow / AlInGaP Amber Color Bins ^[1]

Bin ID	Dominant Wavelength (nm)	
	Minimum	Maximum
A	582.0	584.5
B	584.5	587.0
C	587.0	589.5
D	589.5	592.0
E	592.0	594.5
F	594.5	597.0

Tolerance : ± 1 nm

GaP Orange Color Bins ^[1]

Bin ID	Dominant Wavelength (nm)	
	Minimum	Maximum
A	597.0	600.0
B	600.0	603.0
C	603.0	606.0
D	606.0	609.0
E	609.0	612.0
F	612.0	615.0

Tolerance : ± 1 nm

GaP Green Color Bins ^[1]

Bin ID	Dominant Wavelength (nm)	
	Minimum	Maximum
A	561.5	564.5
B	564.5	567.5
C	567.5	570.5
D	570.5	573.5
E	573.5	576.5

Tolerance : ± 1 nm

AlInGaP Green Color Bins ^[1]

Bin ID	Dominant Wavelength (nm)	
	Minimum	Maximum
A	561.5	564.5
B	564.5	567.5
C	567.5	570.5
D	570.5	573.5
E	573.5	576.5

Tolerance : ± 1 nm

Light Intensity (Iv) Bin Limits^[1]

Intensity (mcd)		
Bin ID	Min.	Max.
A	0.11	0.18
B	0.18	0.29
C	0.29	0.45
D	0.45	0.72
E	0.72	1.10
F	1.10	1.80
G	1.80	2.80
H	2.80	4.50
J	4.50	7.20
K	7.20	11.20
L	11.20	18.00
M	18.00	28.50

Intensity (mcd)		
Bin ID	Min.	Max.
N	28.50	45.00
P	45.00	71.50
Q	71.50	112.50
R	112.50	180.00
S	180.00	285.00
T	285.00	450.00
U	450.00	715.00
V	715.00	1125.00
W	1125.00	1800.00
X	1800.00	2850.00
Y	2850.00	4500.00

Tolerance: $\pm 15\%$.

Note:

1. Bin categories are established for classification of products. Products may not be available in all categories. Please contact your Avago representative for information on currently available bins.

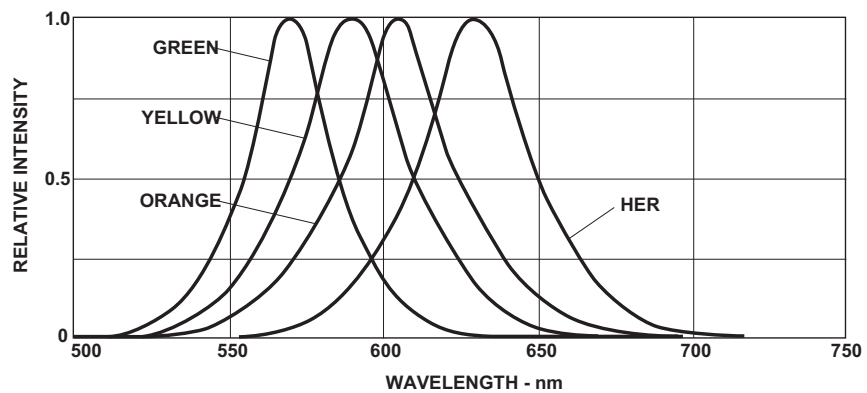


Figure 1. Relative intensity vs. wavelength.

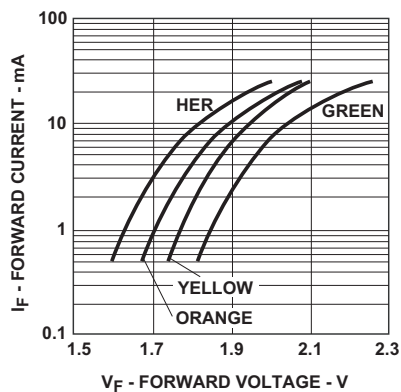


Figure 2. Forward current vs. forward voltage.

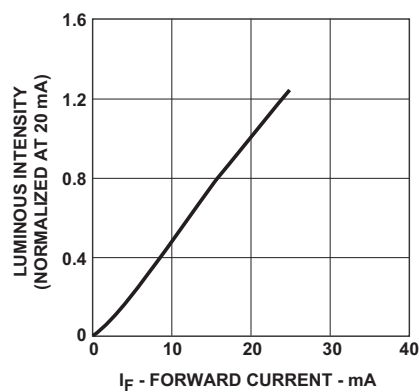


Figure 3. Luminous intensity vs. forward current (all colors).

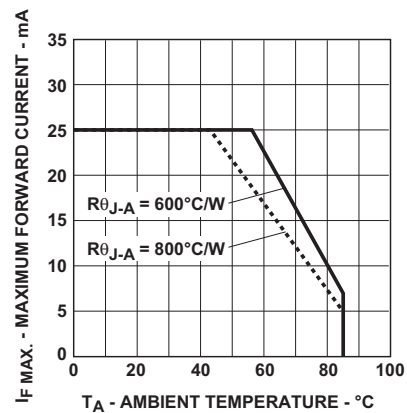


Figure 4. Maximum forward current vs. ambient temperature.

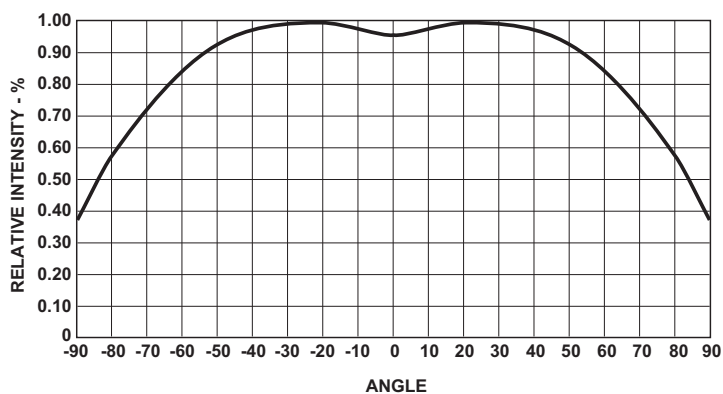


Figure 5. Relative intensity vs. angle for HSMF-C153, C155, C156, C157 and C158.

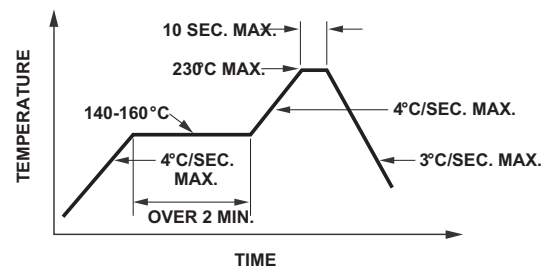


Figure 6. Recommended reflow soldering profile.

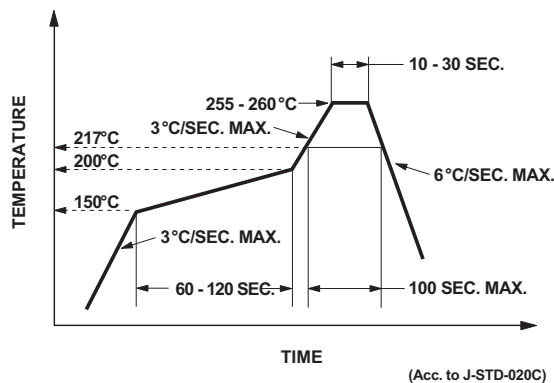
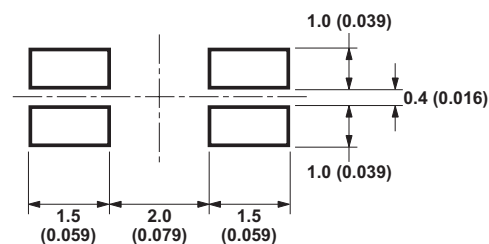


Figure 7. Recommended Pb free reflow soldering profile.



Note: 1. All dimensions in millimeters (inches).

Figure 8. Recommended solder pad pattern.

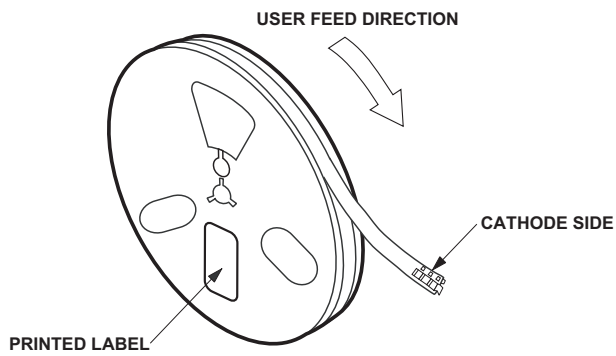
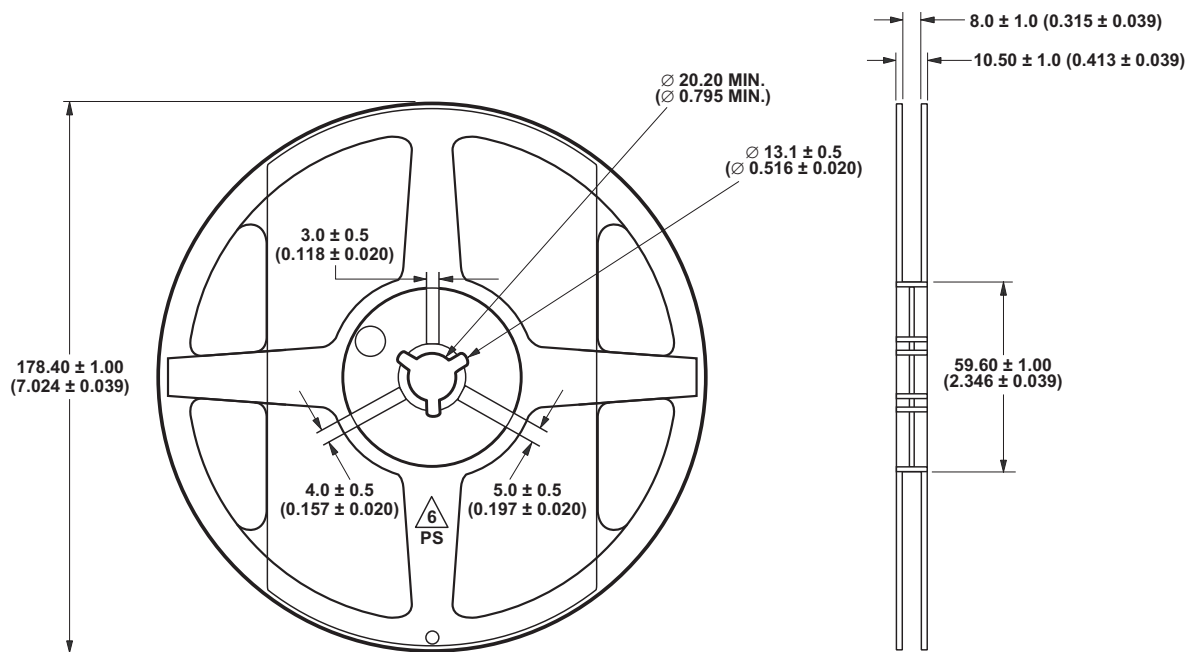


Figure 9. Reeling orientation.



Note:
All dimensions in millimeters (inches).

Figure 10. Reel dimensions.

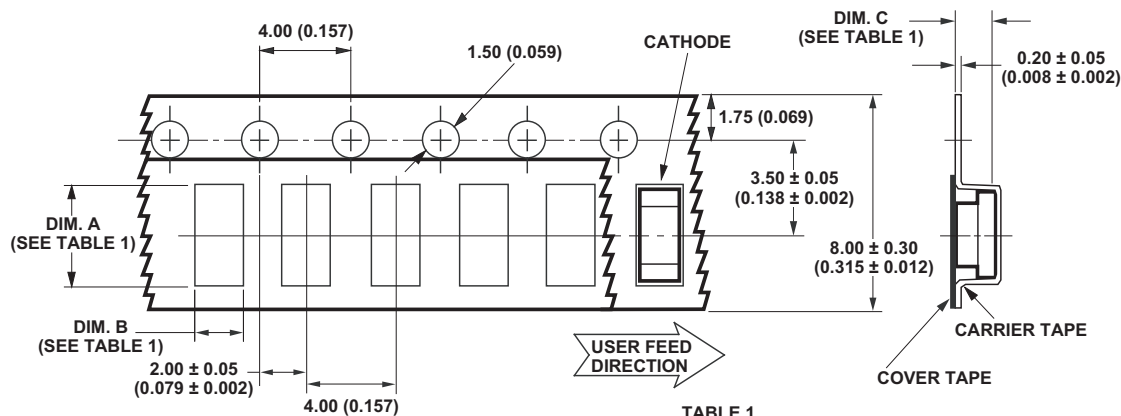


TABLE 1
DIMENSIONS IN MILLIMETERS (INCHES)

PART NUMBER	DIM. A ± 0.10 (0.004)	DIM. B ± 0.10 (0.004)	DIM. C ± 0.10 (0.004)
HSMF-C15x SERIES	3.52 (0.139)	3.02 (0.119)	1.40 (0.055)

Figure 11. Tape dimensions.

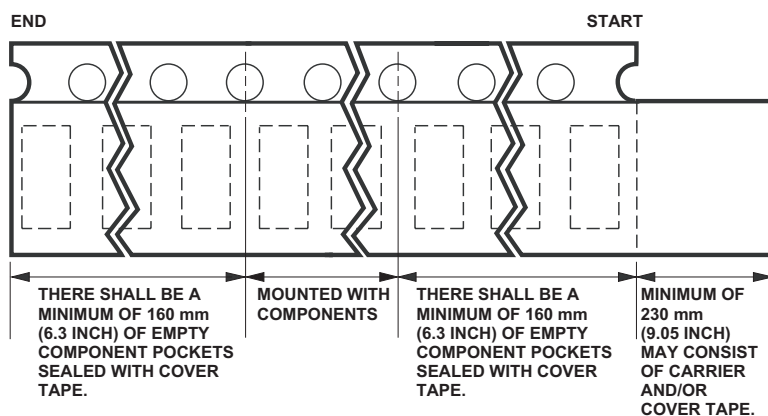


Figure 12. Tape leader and trailer dimensions.

Notes:

1. All dimensions in millimeters (inches).
2. Tolerance is ± 0.1 mm (± 0.004 in.) unless otherwise specified.

Convective IR Reflow Soldering

For more information on IR reflow soldering, refer to Application Note 1060, *Surface Mounting SMT LED Indicator Components*.

Storage Condition:

5 to 30°C @ 60% RH max.

Baking is required under the condition:

- a) Humidity Indicator Card is $>10\%$ when read at $23 \pm 5^\circ\text{C}$
- b) Device exposed to factory conditions $< 30^\circ\text{C}/60\%$ RH more than 672 hours.

Baking recommended condition:

$60 \pm 5^\circ\text{C}$ for 20 hours.

For product information and a complete list of distributors, please go to our website: www.avagotech.com

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